

SEMIPACK® 1

Thyristor / Diode Modules

SKKH 58/16 E

Features

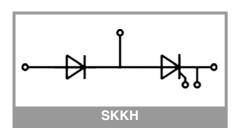
- Heat transfer through aluminium oxide ceramic isolated metal baseplate
- UL recognized, file no. E63532

Typical Applications*

- DC motor control (e. g. for machine tools)
- AC motor soft starters
- Temperature control (e. g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)

Absolute Maximum Ratings								
Symbol	Conditions		Values	Unit				
Chip				•				
I _{T(AV)}	sinus 180°	T _c = 85 °C	55	Α				
		T _c = 100 °C	41	Α				
I _{TRMS}	continuous operation		90	Α				
I _{TSM}	10 ms	T _j = 25 °C	1500	Α				
		T _j = 130 °C	1200	А				
i ² t	10 ms	T _j = 25 °C	11250	A ² s				
	101115	T _j = 130 °C	7200	A ² s				
V_{RSM}			1700	V				
V_{RRM}			1600	V				
V_{DRM}			1600	V				
(di/dt) _{cr}	T _j = 130 °C		140	A/μs				
(dv/dt) _{cr}	T _j = 130 °C		1000	V/µs				
Tj			-40 130	°C				
Module								
T _{stg}			-40 125	°C				
V _{isol}	a.c.; 50 Hz; r.m.s.	1 min	3000	V				
		1 s	3600	V				

Characte	ristics					
Symbol	Conditions	min.	typ.	max.	Unit	
Chip						
V_{T}	T _j = 25 °C, I _T = 180 A			1.5	1.75	V
$V_{T(TO)}$	T _j = 130 °C			0.85	1	V
r _T	T _j = 130 °C			4.00	4.8	mΩ
$I_{DD};I_{RD}$	T _j = 130 °C, V _{DD} :			20	mA	
t_{gd}	$T_j = 25 ^{\circ}\text{C}, I_G = 1 \text{A}, di_G/dt = 1 \text{A}/\mu\text{s}$			1		μs
t_{gr}	$V_D = 0.67 * V_{DRM}$			2		μs
t_{q}	T _j = 130 °C			170		μs
I_{H}	T _j = 25 °C			150	250	mA
IL	$T_j = 25$ °C, $R_G = 33 \Omega$			300	600	mA
V_{GT}	$T_j = 25$ °C, d.c.		2.5			V
I _{GT}	$T_j = 25$ °C, d.c.		100			mA
V_{GD}	T _j = 130 °C, d.c.				0.25	V
I_{GD}	T _j = 130 °C, d.c.				4	mA
$R_{th(j-c)}$	continuous DC	per chip			0.47	K/W
		per module			0.235	K/W
$R_{th(j-c)}$	sin. 180°	per chip			0.49	K/W
		per module			0.245	K/W
$R_{th(j-c)}$	rec. 120°	per chip			0.51	K/W
		per module			0.255	K/W
Module						
R _{th(c-s)}	chip			0.22		K/W
	module			0.11		K/W
Ms	to heatsink M5		4.25		5.75	Nm
M_t	to terminals M5		2.55		3.45	Nm
а					5 * 9,81	m/s²
W				75		g



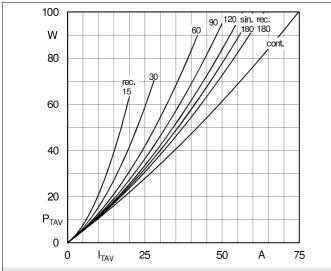


Fig. 1L: Power dissipation per thyristor/diode vs. on-state current

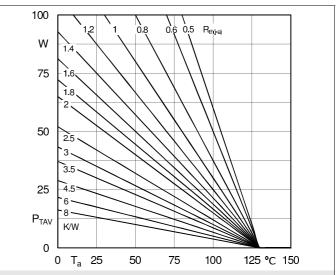


Fig. 1R: Max. power dissipation per chip vs. ambient temperature

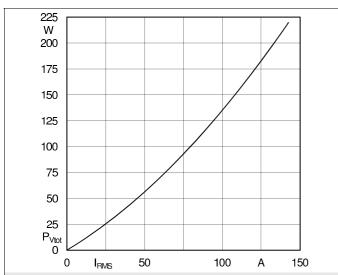


Fig. 2L: Max. power dissipation of one module vs. rms current

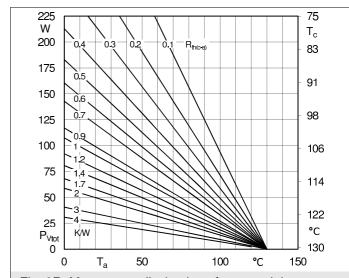


Fig. 2R: Max. power dissipation of one module vs. case temperature

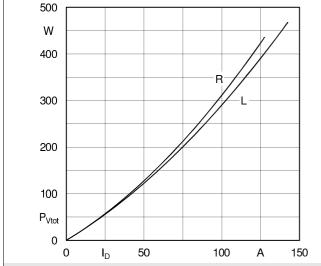


Fig. 3L: Max. power dissipation of two modules vs. direct current

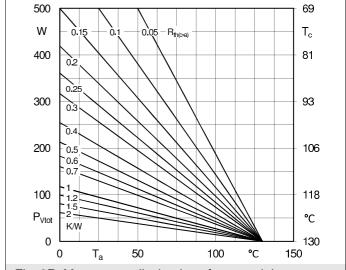


Fig. 3R: Max. power dissipation of two modules vs. case temperature

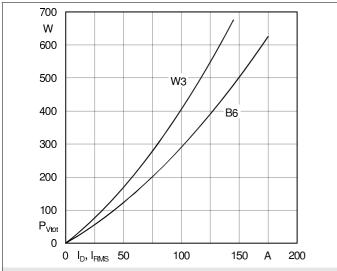


Fig. 4L: Max. power dissipation of three modules vs. direct current

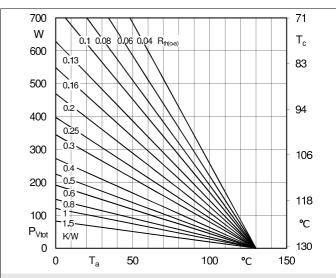


Fig. 4R: Max. power dissipation of three modules vs. case temperature

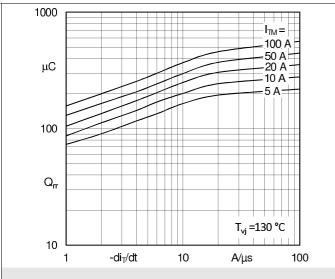


Fig. 5: Recovered charge vs. current decrease

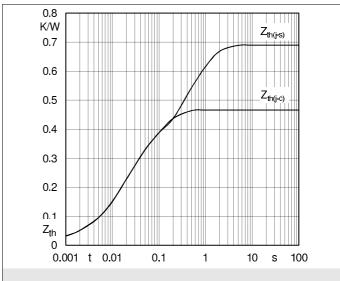


Fig. 6: Transient thermal impedance vs. time

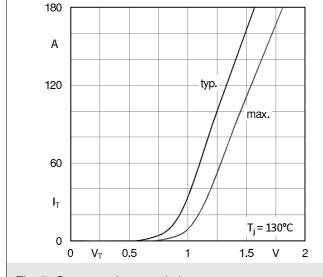


Fig. 7: On-state characteristics

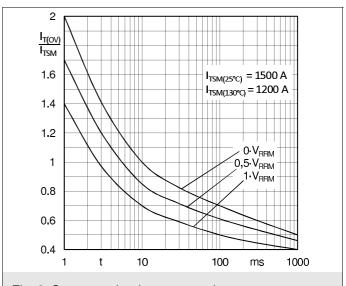
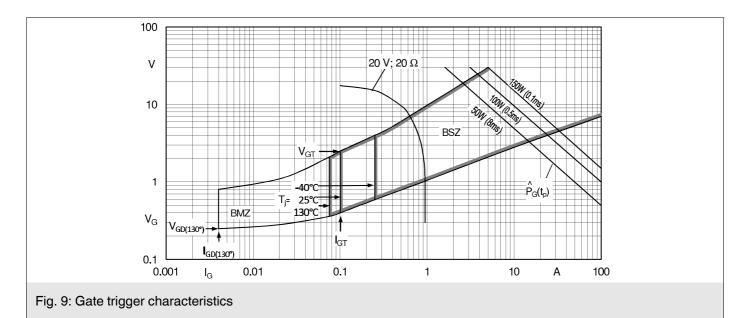
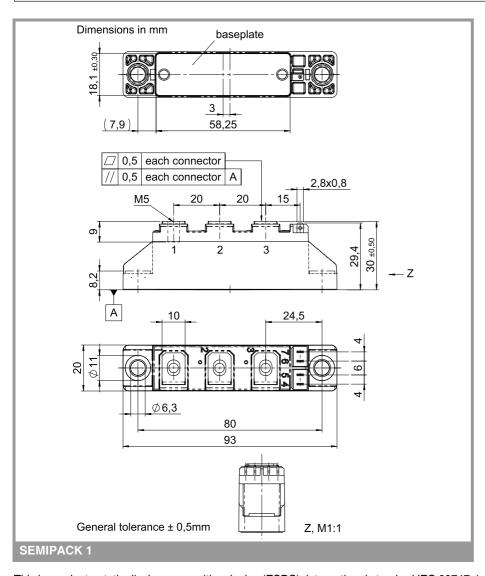
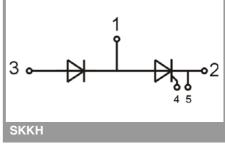


Fig. 8: Surge overload current vs. time







This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

*IMPORTANT INFORMATION AND WARNINGS

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